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A product Line of
Diodes Incorporated

PI3EQX1204-C

12.5Gbps 4-channel, SAS3 ReDriver with Linear Equalization

Features

- 1-12.5Gbps serial link with linear equalizer
- Support SATA Gen1/Gen2/Gen3, SAS2/3, and XAUI protocol
- Supporting 4 differential channels
- Handle up to 34dB channel loss (42" FR4 trace or 10 meters or SAS3 cable)
- Independent channel configuration of receiver equalization, output swing and flat gain
- Rate and Coding Agnostic
- Transparent to link training, OOB, Idle
- 260mW per channel power dissipation with 700 mVpp output swing
- Pin strap and I²C selectable device programming
- 4-bit selectable address bit for I²C
- Supply Voltage: 3.3V±0.3V
- Industrial Temperature Range: -40°C to 85°C
- Packaging (Pb-free & Green):
  - 42-contact TQFN (9mm x3.5mm)

Description

The PI3EQX1204-C is a SAS3, 4 differential channels ReDriver. The device provides programmable linear equalization, output swing and flat gain, by either pin strapping option or I²C Control, to optimize performance over a variety of physical mediums by reducing Inter-symbol interference.

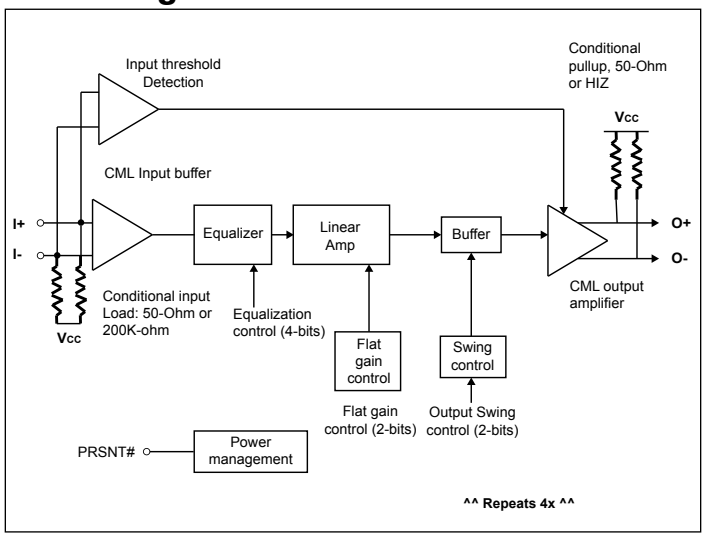
PI3EQX1204-C supports four 100-Ohm Differential CML data I/O's and extends the signals across other distant data pathways on the user's platform.

The integrated equalization circuitry provides flexibility with signal integrity of the signal before the ReDriver, whereas the integrated linear amplifier/buffer circuitry provides flexibility with signal integrity of the signal after the ReDriver.

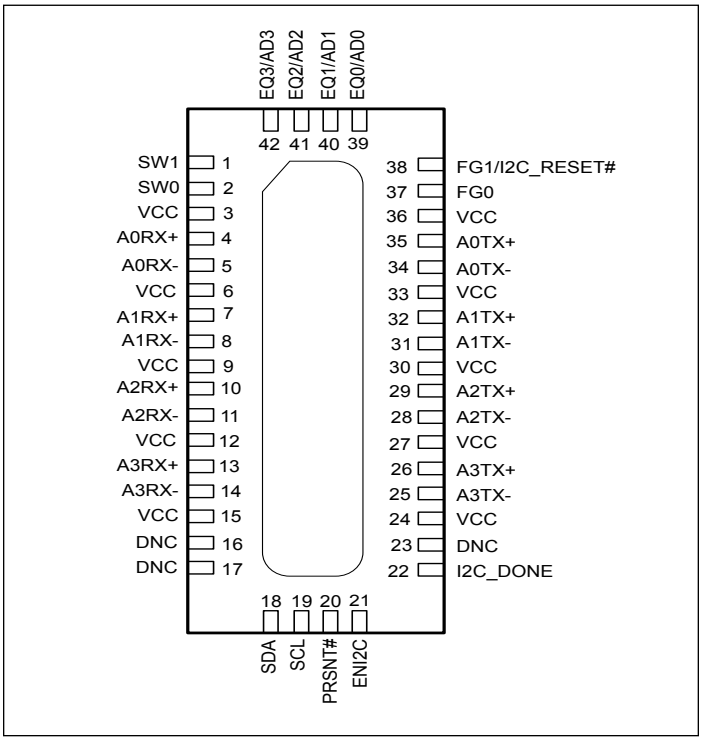
Application

Rack Server, JBOD storage

Block Diagram



Pin Configuration (Top-Side View)



Pin Description

Pin #	Pin Name	Type	Description
Data Signals			
4 5	A0RX+ A0RX-	I I	CML inputs for Channel A0, with internal 50-Ohm pull-up and ~200K-Ohm pull-up otherwise.
35 34	A0TX+ A0TX-	O O	CML outputs for Channel A0, with internal 50-Ohm pull-up and high impedance otherwise.
7 8	A1RX+ A1RX-	I I	CML inputs for Channel A1, with internal 50-Ohm pull-up and ~200K-Ohm otherwise.
32 31	A1TX+ A1TX-	O O	CML outputs for Channel A1, with internal 50-Ohm pull-up and high impedance otherwise.
10 11	A2RX+ A2RX-	I I	CML inputs for Channel A2, with internal 50-Ohm pull-up and ~200K-Ohm otherwise.
29 28	A2TX+ A2TX-	O O	CML outputs for Channel A2, with internal 50-Ohm pull-up and high impedance otherwise.
13 14	A3RX+ A3RX-	I I	CML inputs for Channel A3, with internal 50-Ohm pull-up and ~200K-Ohm otherwise.
26 25	A3TX+ A3TX-	O O	CML outputs for Channel A3, with internal 50-Ohm pull-up and high impedance otherwise.
Control Signals			
19	SCL	I/O	I^2C SCL Clock. In Master mode (ENI2C floating), SCL is an output. Otherwise it is an input.
18	SDA	I/O	I^2C SDA data input/output.
42, 41, 40, 39	AD[3:0]	I	I^2C programmable address bits, with internal 100k-Ohm pull-up.
20	PRSNT#	I	This pin is active in both PIN mode(ENI2C=LOW) and I^2C mode (ENI2C=HIGH). Cable present detect input. This pin has internal 100K-ohm pull-up. When High, a cable is not present, and the device is put in lower power mode. When LOW, the device is enabled and in normal operation.
21	ENI2C	I	When LOW, each channel is programmed by the external pin voltage. When HIGH, each channel is programmed by the data stored in the I^2C bus. When floating, master mode (Read External EEPROM)
42, 41, 40, 39	EQ[3:0]	I	Inputs with internal 100k-Ohm pull-up. This pins set the amount of Equalizer Boost in all channel when ENI2C is LOW.
1, 2	SW[1:0]	I	Inputs with internal 100k-Ohm pull-up. This pin sets the output Voltage Level in all channel when ENI2C is LOW.
38, 37	FG[1:0]	I	Inputs with internal 100KΩ pull up resistor. Sets the output flat gain level on all channels when ENI2C is low.
38	I^2C_RESET#	I	Inputs with internal 100KΩ pull up resistor. Reset pin for I^2C. When set low will reset the registers to default state.

Pin #	Pin Name	Type	Description
22	I^2C_DONE	O	Valid register load status output, use for daisy chain master LOW = External EEPROM load failed HIGH = External EEPROM load passed
16, 17, 23	DNC		Do Not Connect
Power Pins			
3, 6, 9, 12, 15, 24, 27, 30, 33, 36	V_{CC}	PWR	3.3V Supply Voltage
EP	GND	PWR	Exposed pad. Supply Ground

Description of Operation

Power Enable function:

One pin control or I²C control, when PRSNT# is set to HIGH, the IC goes into power down mode, both input and output termination set to 200K and High impedance respectively. Individual Channel Enabling is done through the I²C register programming.

Equalization Setting:

EQ[3:0] are the selection pins for the equalization selection for each channel.

Table 1. Equalization Setting

Equalizer setting							
EQ3	**EQ2**	**EQ1**	**EQ0**	**@ 3GHz**	**@ 4GHz**	**@ 5GHz**	**@ 6GHz**
0	0	0	0	3.6	4.5	5.5	6.8
0	0	0	1	4	5.1	6.2	7.6
0	0	1	0	4.4	5.6	6.9	8.4
0	0	1	1	4.7	6.1	7.5	9.1
0	1	0	0	5.1	6.6	8.1	9.8
0	1	0	1	5.5	7.1	8.7	10.4
0	1	1	0	5.9	7.6	9.2	11
0	1	1	1	6.2	8	9.7	11.5
1	0	0	0	6.6	8.5	10.2	12
1	0	0	1	6.9	8.9	10.7	12.5
1	0	1	0	7.3	9.3	11.1	12.9
1	0	1	1	7.6	9.7	11.5	13.3
1	1	0	0	8	10.1	11.9	13.7
1	1	0	1	8.2	10.5	12.3	14.1
1	1	1	0	8.6	10.8	12.7	14.4
1	1	1	1	8.9	11.1	13	14.7

Flat Gain Setting:

FG[1:0] are the selection bits for the DC value.

Table 2. Flat Gain Setting

Flat Gain Setting		
FG1	**FG0**	**dB**
0	0	-3.5
0	1	-1.5
1	0	0.5
1	1	2.5

Swing Setting:

Swing Setting: SW[1:0] are the selection bits for the output swing value.

Table 3. Swing Setting

SW1	SW0	mVp-p
0	0	700
0	1	800
1	0	900
1	1	1000

I²C Programming

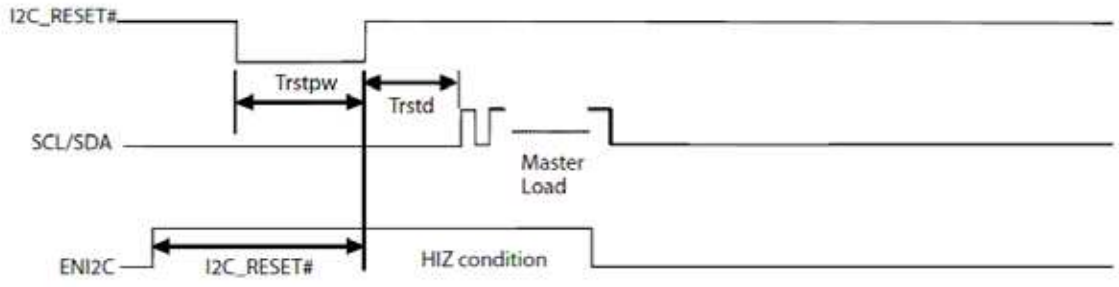
Address assignment							
A6	**A5**	**A4**	**A3**	**A2**	**A1**	**A0**	**R/W**
1	1	1	AD3	AD2	AD1	AD0	1=R, 0=W

BYTE 0 Reserved					
BYTE 1 Reserved					
BYTE 2					
Bit	**Type**	**Power up condition**		**Control affected**	**Comment**
7	R/W	0		A3 Power down	1 = Power down
6	R/W	0		A2 Power down	
5	R/W	0		A1 Power down	
4	R/W	0		A0 Power down	
3	R/W	0			
2	R/W	0			
1	R/W	0			
0	R/W	0			
BYTE 3					
Bit	**Type**	**Power up condition**		**Control affected**	Comment
7	R/W	0	Channel A0 configuration	EQ3	Equalizer
6	R/W	0		EQ2	
5	R/W	0		EQ1	
4	R/W	0		EQ0	
3	R/W	0		FG1	Flat gain
2	R/W	0		FG0	
1	R/W	0		SW1	Swing
0	R/W	0		SW0	
BYTE 4					
Bit	**Type**	**Power up condition**		**Control affected**	Comment
7	R/W	0	Channel A1 configuration	EQ3	Equalizer
6	R/W	0		EQ2	
5	R/W	0		EQ1	
4	R/W	0		EQ0	
3	R/W	0		FG1	Flat gain
2	R/W	0		FG0	
1	R/W	0		SW1	Swing
0	R/W	0		SW0	

I²C Programming cont.

BYTE 5					
Bit	**Type**	**Power up condition**		**Control affected**	Comment
7	R/W	0	Channel A2 configuration	EQ3	Equalizer
6	R/W	0		EQ2	
5	R/W	0		EQ1	
4	R/W	0		EQ0	
3	R/W	0		FG1	Flat gain
2	R/W	0		FG0	
1	R/W	0		SW1	Swing
0	R/W	0		SW0	
BYTE 6					
Bit	**Type**	**Power up condition**		**Control affected**	Comment
7	R/W	0	Channel A3 configuration	EQ3	Equalizer
6	R/W	0		EQ2	
5	R/W	0		EQ1	
4	R/W	0		EQ0	
3	R/W	0		FG1	Flat gain
2	R/W	0		FG0	
1	R/W	0		SW1	Swing
0	R/W	0		SW0	
BYTE 7-15 with '0' power up condition Reserved					

Reset and I²CM Timing Diagram



Recommended minimum reset pulse width T_{rstpw}= 1µs
I²C master cycle start from I2C_RESET# pulse go high, Trstd = 200µs
ENI2C = HIZ to I2C_RESET#(high) (min), Ti2cm_rst = 1 uS.

I²C Operation

The integrated I²C interface operates as a master or slave device depending on the pin ENI2C being HIZ or HIGH respectively. Standard mode (100Kbps) is supported with 7-bit addressing. The data byte format is 8-bit bytes, and supports the format of indexing to be compatible with other bus devices. In the Slave mode (ENI2C = HIGH), the device supports Read/Write. The bytes must be accessed in sequential order from the lowest to the highest byte with the ability to stop after any complete byte has been transferred. Address bits A3 to A0 are programmable to support multiple chips environment. The Data is loaded until a Stop sequence is issued.

In the master mode (ENI2C = HIZ), PI3EQX1204-C supports up to 16 masters connected in daisy chain through connecting I²C_DONE pin to I²C_RESET# pin of the next part.

Master EEPROM data starting address for device address:

I²C address: AD3, AD2, AD1, AD0	Data starting location
0000	00H
0001	10H
0010	20H
0011	30H
0100	40H
0101	50H
0110	60H
0111	70H
1000	80H
1001	90H
1010	A0H
1011	B0H
1100	C0H
1101	D0H
1110	E0H
1111	F0H

Transferring Data

Every byte put on the SDA line must be 8-bits long. Each byte has to be followed by an acknowledge bit. Data is transferred with the most significant bit (MSB) first (see the I²C Data Transfer diagram). The PI3EQX1204-C will never hold the clock line SCL LOW to force the master into a wait state.

Acknowledge

Data transfer with acknowledge is required from the master. When the master releases the SDA line (HIGH) during the acknowledge clock pulse, the PI3EQX1204-C will pull down the SDA line during the acknowledge clock pulse so that it remains stable LOW during the HIGH period of this clock pulse as indicated in the I²C Data Transfer diagram. The PI3EQX1204-C will generate an acknowledge after each byte has been received.

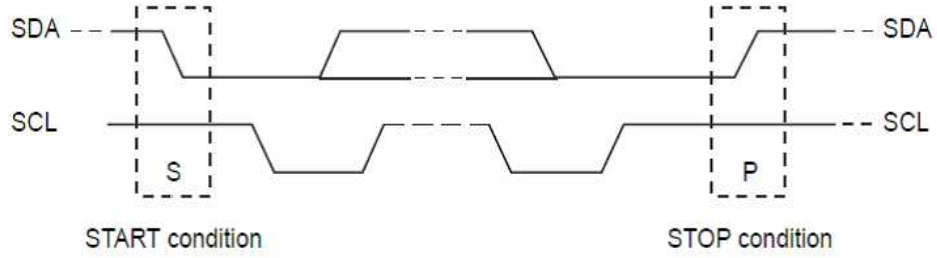
Data Transfer

A data transfer cycle begins with the master issuing a start bit. After recognizing a start bit, the PI3EQX1204-C will watch the next byte of information for a match with its address setting. When a match is found it will respond with a read or write of data on the following clocks. Each byte must be followed by an acknowledge bit, except for the last byte of a read cycle which ends with a stop bit. For a write cycle, the first data byte following the address byte is an index byte that is used by the PI3EQX1204-C. Data is transferred with the most significant bit (MSB) first.

I2C Data Transfer

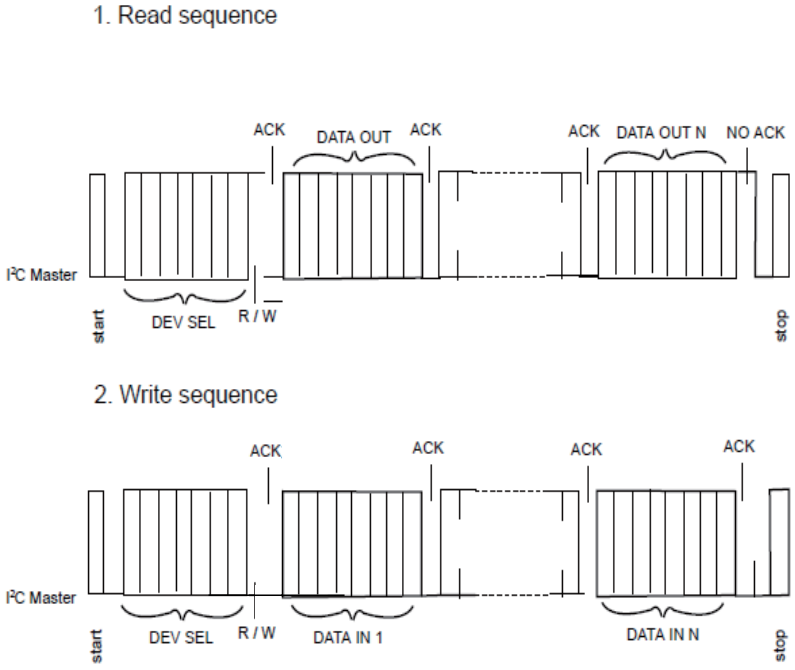
Start & Stop Conditions

A HIGH to LOW transition on the SDA line while SCL is HIGH indicates a START condition. A LOW to HIGH transition on the SDA line while SCL is HIGH defines a STOP condition, as shown in the figure below



I²C START and STOP conditions.

I²C Data Transfer



Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	–65°C to +150°C
Supply Voltage to Ground Potential	–0.5V to +4.6V
DC SIG Voltage	–0.5V to V_{CC}+0.5V
Output Current	–25mA to +25mA
Power Dissipation Continuous	2.1W
Junction Temperature Tj.	125°C
ESD, HBM.	–2kV to +2kV

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical characteristics:

LVCMOS I/O DC Specifications (V_{CC} = 3.3 ± 0.3V, T_A = -40 to 85°C)

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
V_{IH}	DC input logic high		V_{CC}/2 + 0.7		V_{C}C + 0.3	V
V_{IL}	DC input logic low		-0.3		V_{CC}/2 - 0.7	V
V_{OH}	At IOH = -200µA		V_{CC} + 0.2			V
V_{OL}	At IOL = -200µA				0.2	V
V_{hys}	Hysteresis of Schmitt trigger input		0.8			V

SDA and SCL I/O for I2C-bus (V_{CC} = 3.3 ± 0.3V, T_A = -40 to 85°C)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{IH}	DC input logic high		V_{CC}/2 + 0.7		V_{CC} + 0.3	V
V_{IL}	DC input logic low		-0.3		V_{CC}/2 - 0.7	V
V_{OL}	DC output logic low	I_{OL} = 3mA			0.4	V
V_{hys}	Hysteresis of Schmitt trigger input		0.8			V
t_{of}	Output fall time from VIHmin to VILmax with bus cap. 10-400pF				250	ns
f_{SCLK}	SCLK clock frequency				100	kHz

High speed I/O AC/DC Specifications (V_{CC} = 3.3 ± 0.3V, T_A = -40 to 85°C)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
C_{RX}	RX AC coupling capacitance			220		nF
S_{11}	Input return loss	10MHz to 6GHz differential		11.0		dB
		1GHz to 6GHz common mode		5.0		
S_{22}	Output return loss	10MHz to 6GHz differential		11.5		dB
		1GHz to 6GHz common mode		4.8		
R_{IN}	DC single-ended input impedance			50		Ω
	DC Differential Input Impedance			100		

High speed I/O AC/DC Specifications cont.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
R_{OUT}	DC single-ended output impedance			50		Ω
	DC Differential output Impedance			100		
Z_{RX-HIZ}	DC input CM input impedance during reset or power down			200		kΩ
$V_{RX-DIFF-PP}$	Differential Input Peak-to-peak Voltage	Operational			1.2	Vppd
	Input source common-mode noise	DC – 200MHz			150	mVpp
$T_{TX-IDLE-SET-TO-IDLE}$	Max time to electrical idle after sending an EIOS			4	8	ns
$T_{TX-IDLE-TO-DIFF-DATA}$	Max time to valid diff signal after leaving electrical idle			4	8	ns
Vcc	Power supply voltage		3	3.3	3.6	V
P_{max}	Max Supply power	PRSNT#=0			1.3	W
I_{max}	Max Supply current				360	mA
P_{idle}	Supply power	PRSNT#=1			14.4	mW
t_{pd}	Latency	From input to output		0.5		ns
G_P	Peaking gain (Compensation at 6GHz, relative to 100MHz, 100mVp-p sine wave input)	EQ<3:0> = 1111 EQ<3:0> = 1000 EQ<3:0> = 0000		15.4 12.5 7.1		dB
		Variation around typical	-3		+3	dB
G_F	Flat gain (100MHz, EQ<3:0> = 1000, SW<1:0> = 10)	FG<1:0> = 11 FG<1:0> = 10 FG<1:0> = 01 FG<1:0> = 00		2 0 -2 -4		dB
		Variation around typical	-3		+3	dB
V_{1dB_100M}	-1dB compression point of output swing (at 100MHz)	SW<1:0> = 11 SW<1:0> = 10 SW<1:0> = 01 SW<1:0> = 00		1370 1280 1040 920		mVppd
V_{1dB_6G}	-1dB compression point of output swing (at 6GHz)	SW<1:0> = 11 SW<1:0> = 10 SW<1:0> = 01 SW<1:0> = 00		1000 940 700 600		mVppd
V_{Coup}	Channel isolation	100MHz to 6GHz, Figure 1 (Note 1)		25		dB

High speed I/O AC/DC Specifications cont.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Vnoise_input	Input-referred noise	100MHz to 6GHz, FG<1:0> = 11, EQ<3:0> = 0000, Figure 2		0.5		mV_{RMS}
		100MHz to 6GHz, FG<1:0> = 11, EQ<3:0> = 1010, Figure 2		0.4		
Vnoise_output	Output-referred noise (Note 2)	100MHz to 6GHz, FG<1:0> = 11, EQ<3:0> = 0000, Figure 2		0.7		mV_{RMS}
		100MHz to 6GHz, FG<1:0> = 11, EQ<3:0> = 1010, Figure 2		0.8	1.6	

Note: (1) Measured using a vector-network analyzer (VNA) with -15dBm power level applied to the adjacent input. The VNA detects the signal at the output of the victim channel. All other inputs and outputs are terminated with 50Ω.

(2) Guaranteed by design and characterization.

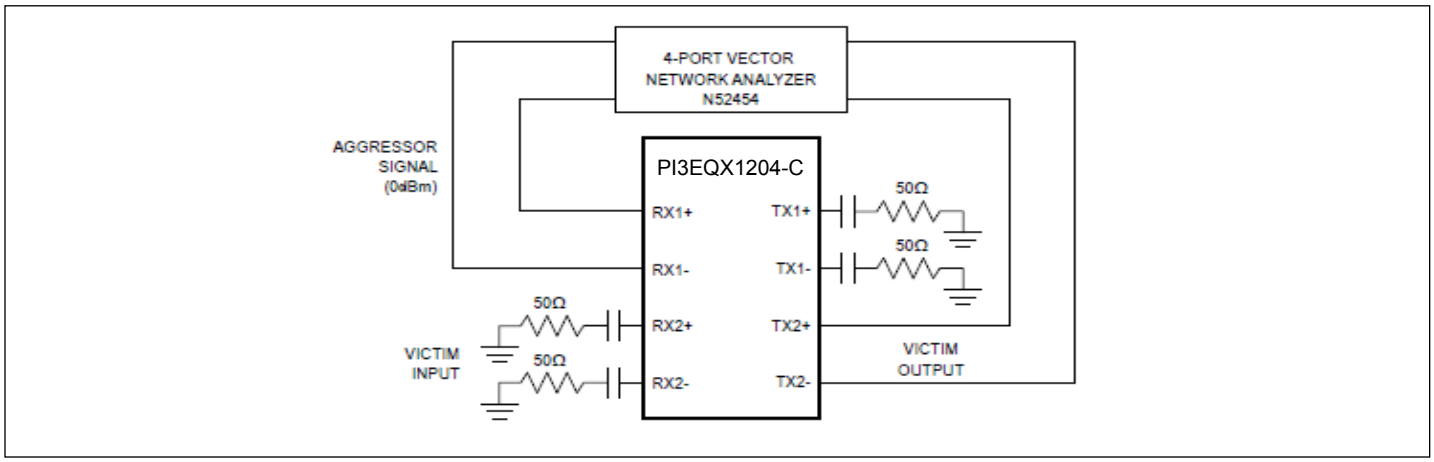


Figure 1. Channel-isolation test configuration

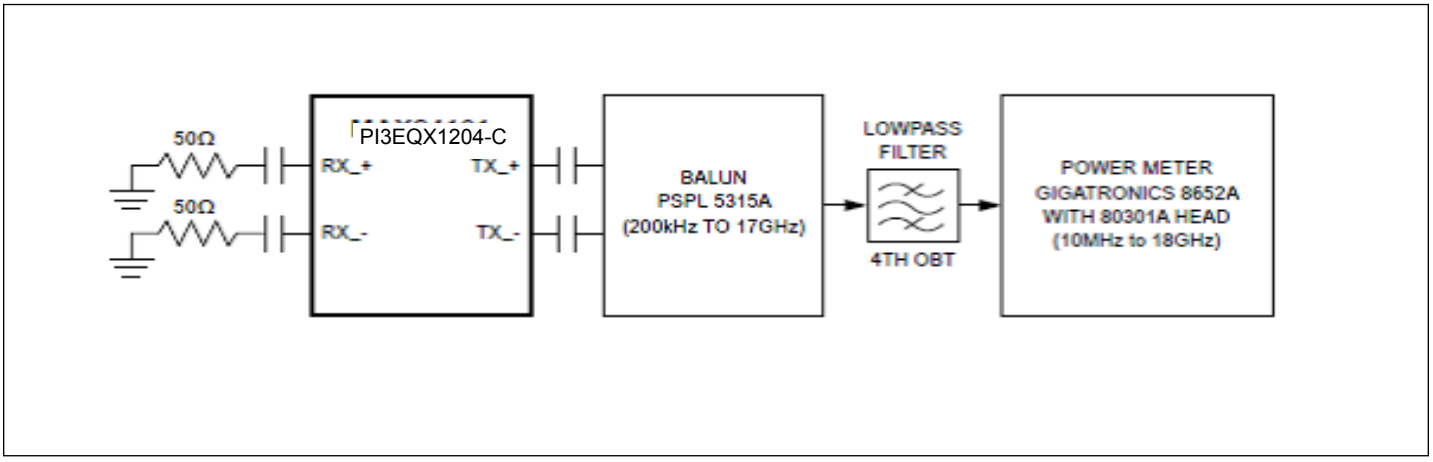
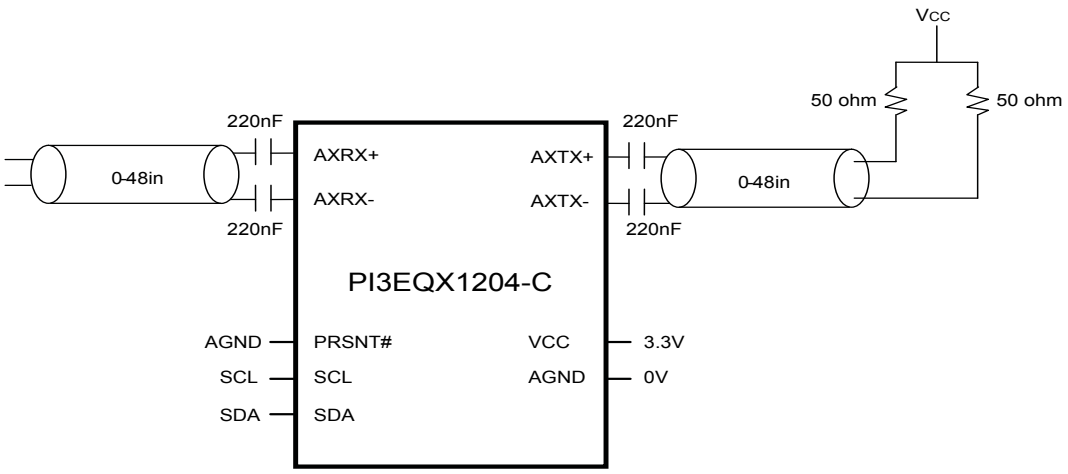


Figure 2. Noise test configuration

ESD Specification

- 2000V HBM
- 500V CDM

Application Diagram



AC/DC Specifications - SCL/SDA for I²C BUS

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
V_{IH}	DC input logic high		$V_{CC}/2$ + 0.7		V_{CC} + 0.3	V
V_{IL}	DC input logic low		-0.3		$V_{CC}/2$ - 0.7	V
V_{OL}	DC output logic low	I_{OL} = 3mA			0.4	V
Ipullup	Current Through Pull-Up Resistor or Current Source	High Power specification	3.0		3.6	mA
VDD	Nominal Bus Voltage		3.0		3.6	V
Ileak-bus	Input leakage per bus segment		-200		200	uA
Ileak-pin	Input leakage per device pin			-15		uA
CI	Capacitance for SDA/SCL				10	pF
Freq	Bus Operation Frequency				100k	Hz
TBUF	"Bus Free Time Between Stop and Start condition"		1.3			us
THD:STA	Hold time after (Repeated) Start condition. After this period, the first clock is generated.	At Ipull-up, Max	0.6			us
TSU:STA	Repeated start conidtion setup time		0.6			us
TSU:STO	Stop condition setup time		0.6			us
THD:DAT	Data hold time		0			ns
TSU:DAT	Data setup time		100			ns
Tlow	Clock low period		1.3			us
Thigh	Clock high period		0.6		50	us
tF	Clock/Data fall time				300	ns
tR	Clock/Data rise time				300	ns
tpor	"Time in which a device must be operation after power-on reset"				500	ms

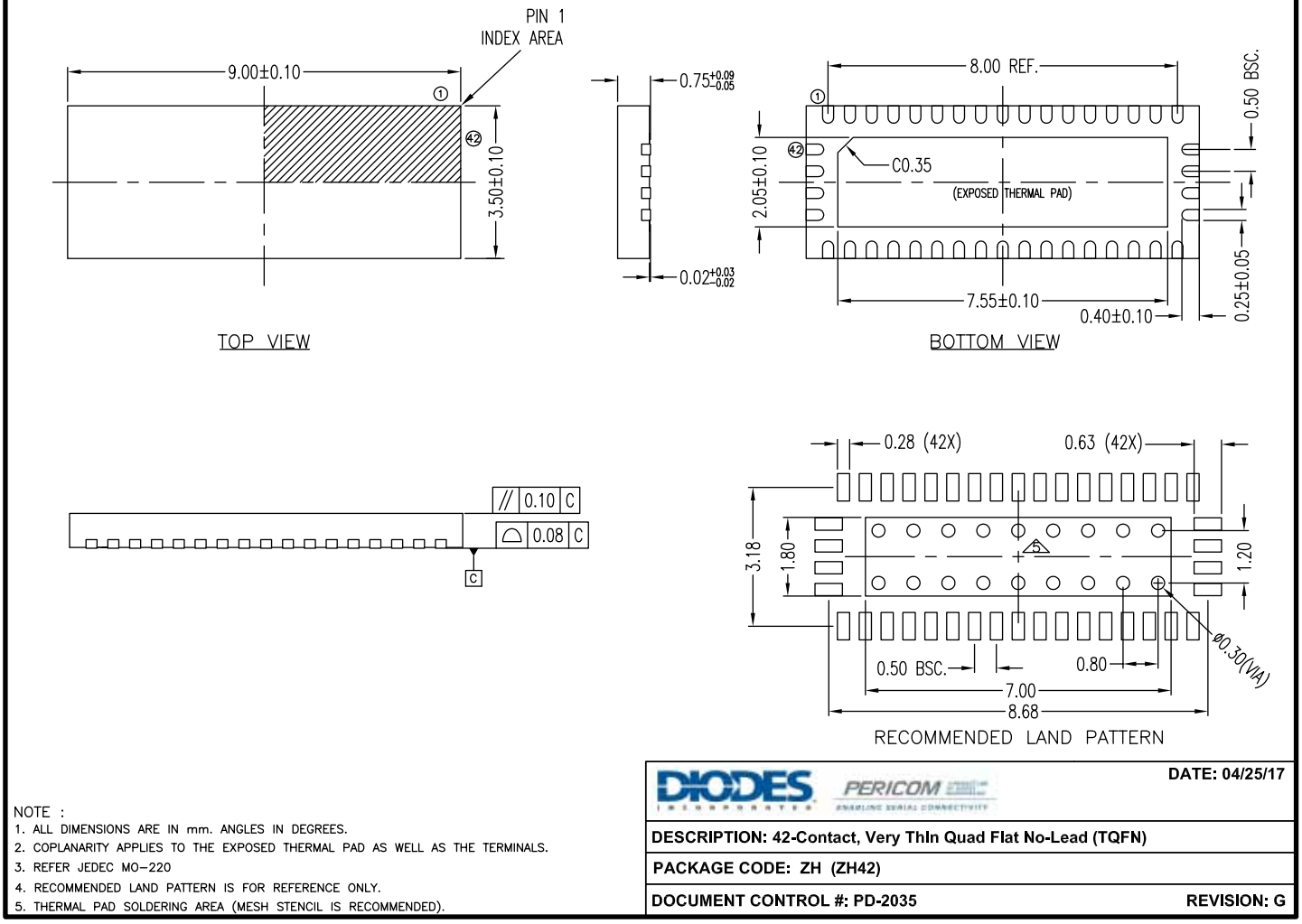
Note: (1) Recommended value.

(2) Recommended maximum capacitance load per bus segment is 400pF.

(3) Compliant to I2C physical layer specification.

(4) Ensured by Design. Parameter not tested in production.

Package Mechanical: 42-Contact TQFN (ZH)



NOTE :
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO–220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL IS RECOMMENDED).

DATE: 04/25/17

DESCRIPTION: 42-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZH (ZH42)

DOCUMENT CONTROL #: PD-2035 REVISION: G

17-0266

Note: For latest package info, please check: https://www.diodes.com/design/support/packaging/pericom-packaging/

Ordering Information

Ordering Number	Package Code	Package Description
PI3EQX1204-CZHE	ZH	42-Contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PI3EQX1204-CZHEX	ZH	42-Contact, Thin Fine Pitch Quad Flat No-Lead (TQFN), Tape & Reel

Notes:

- **Thermal characteristics can be found on the company web site at www.pericom.com/packaging/**
- **E = Pb-free and Green**
- **X suffix = Tape/Reel**

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